

a main body; and

a conductive layer provided on said main body, said conductive layer having a conductive pattern, said conductive pattern having at least one bonding area [configured to correspond to the plurality of bumps of the part], said conductive layer having at least one of an isolated notch part and a recess located proximate to and not extending within said at least one bonding area[, wherein said notch part or said recess is configured to extend in a direction traverse to an ultrasonic vibrating direction of the ultrasonic bonding],

wherein said notch part or said recess partially narrows said conductive pattern to form a narrow pattern part.

9. (Once Amended) [The] A circuit board [as claimed in claim 7,] comprising:

a main body; and

a conductive layer provided on said main body, said conductive layer having a conductive pattern, said conductive pattern having at least one bonding area, said conductive layer having at least one of an isolated notch part and a recess located proximate to and not extending within said at least one bonding area,

wherein said notch part or said recess narrows said conductive pattern at said at least one bonding area.

Please add the following new claims:

--13. A circuit board comprising:

a main body; and

a conductive layer provided on said main body, said conductive layer having a conductive pattern, said conductive pattern having: